#### **IEEE SW Test Workshop** Semiconductor Wafer Test Workshop



# CO2 Composite Spray Technology for Probe Card Cleaning



#### David Jackson Cool Clean Technologies

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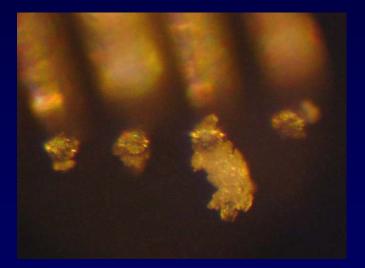
### **Resistive Surface Contamination**



- Metal Oxides (Sn, Pb, Al)
- Passivation
- Silicon Nitride
- Polymers (plasticizers/fibers)
- Lapping Compounds
- Adhesive Residues
- Outgas Compounds
- Metals (solder, Al)
- Human Contaminants
- Cleaning Residues
- Solder Flux

# **Cleaning and Cleanliness Issues**

Contamination tends to bond/adhere in cohesive layers...



Contamination generates more contamination.

#### **Contaminations:**

- A mix of transferred metals, organics, inorganics, ionics and adsorbed films
- Thin and thick layers/films

#### Contact Surfaces:

- Surface area (contact zone) changes over time
- Small/complex topography (curved, pointed, crowned)

#### **Cleaning Processes:**

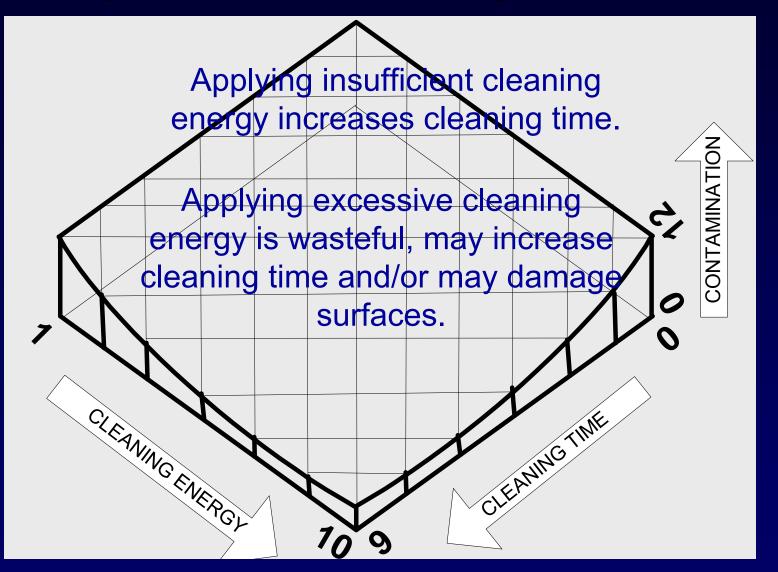
- Incompatibilities (damage/efficacy)
- Variability/Quality
- Long cleaning times (manual methods)

### Cleaning Methods (probe/socket)

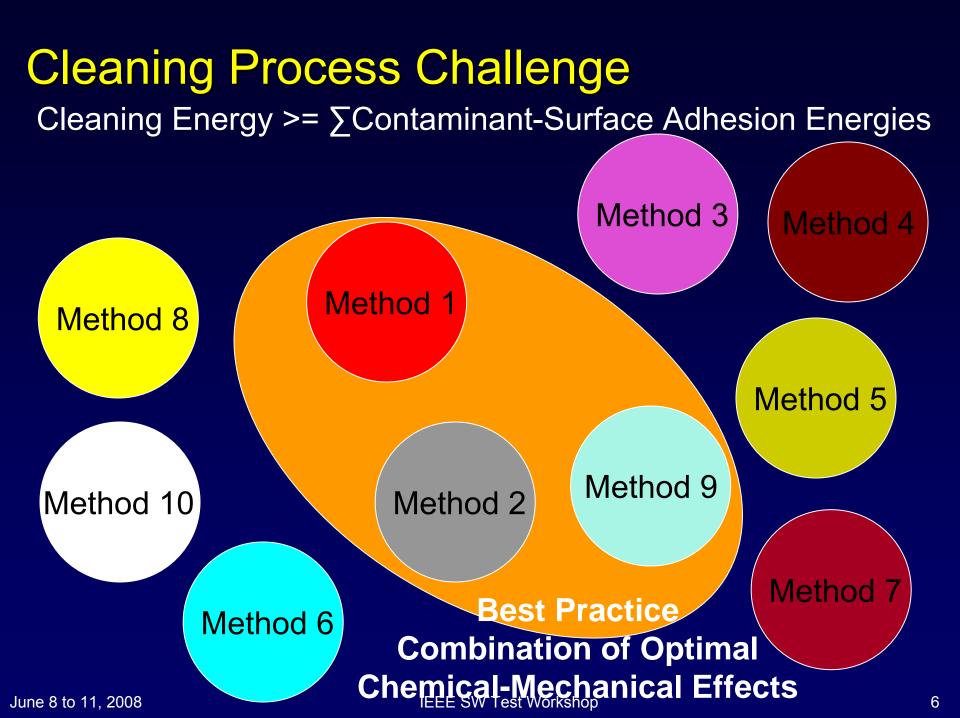
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Method	N	ΙII	<u>C</u>	
<ol> <li>WC Plate</li> <li>Lapping Films</li> <li>Metal/Polymer Brush</li> <li>Ceramic Block</li> <li>Polymer Sheets</li> <li>Microabrasive Spray</li> <li>Camel Hair Brushing</li> <li>IPA Wet Brushing</li> </ol>	X X X		X	<ul> <li>Manual</li> <li>Direct Contact</li> <li>Low Capital</li> <li>High Labor</li> </ul>
<ol> <li>Weak Acid Cleaning</li> <li>Ultrasonic Cleaning</li> <li>Plasma Cleaning</li> </ol>	X X	X X	X X	<ul> <li><u>Automated</u></li> <li>✓ Non-Contact</li> <li>✓ High Capital</li> <li>✓ Low Labor</li> </ul>
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### **Cleaning Process Challenge**



Adapted from "Theory of Cleaning", B.N.Ellis, IEEE SW Test Workshop Circuit World, Vol.12 No.1, 1985



### **Cleaning Process Challenge**

The most desirable cleaning process:

- ✓ Non-destructive (contact surface/peripheral surfaces)
- Minimal or no human contact
- ✓ Robust (in terms of energy control)
- ✓ <u>Both</u> mechanical and chemical cleaning actions
- $\checkmark$  Ability to clean dense and complex surfaces
- ✓ Fast (less cleaning labor/time)
- ✓ Low cost-per-clean
- ✓ Minimal or no cleaning agent by-products
- ✓ Acceptable ROI

### CO<sub>2</sub> Cleaning Technology

CO<sub>2</sub> technology has been used to produce consistently clean surfaces for high-tech products such as spacecraft devices, optical devices, sensors, lasers, disk drives, air bags, medical devices and *probe cards*...

#### **Treatment Schemes**

- Composite CO<sub>2</sub> Spray \*
- Immersion Solvent (Liquid)
- Extraction Solvent (Supercritical)
- Atmospheric Plasma \*
- Low Pressure Plasma
- UV-CO<sub>2</sub> Treatment
- Plasma-CO<sub>2</sub> \*
- Laser-CO<sub>2</sub>\*
- Microabrasive-CO<sub>2</sub>\*

> Hybrid Processes

\* - Probe cleaning candidates

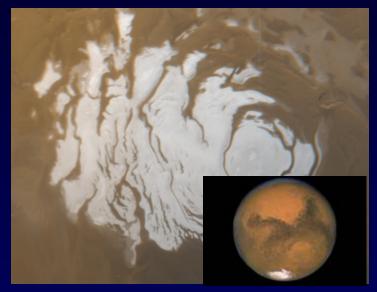
### CO<sub>2</sub> is Abundant

A recycled by-product from industrial and natural sources such as refineries, CaCO<sub>3</sub> wells, and bakeries.

A recyclable and renewable resource.

Major commercial uses include beverage carbonation, fire extinguishing and welding.

#### **South Pole - Mars**







#### CO<sub>2</sub> is Safe

<u>Solvent</u>	Ozone Depleting Potential <u>(ODP)</u>	OSHA <u>PEL</u> (ppm)	VOC
Carbon Dioxide	None	5,000	No
Isopropyl Alcohol	~0	400	Yes
Acetone	~0	1000	No
Trichloroethylene	~0	50	Yes
1,1,1-Trichloroethane	0.15	350	Yes
n-Propyl Bromide	~0	100	Yes

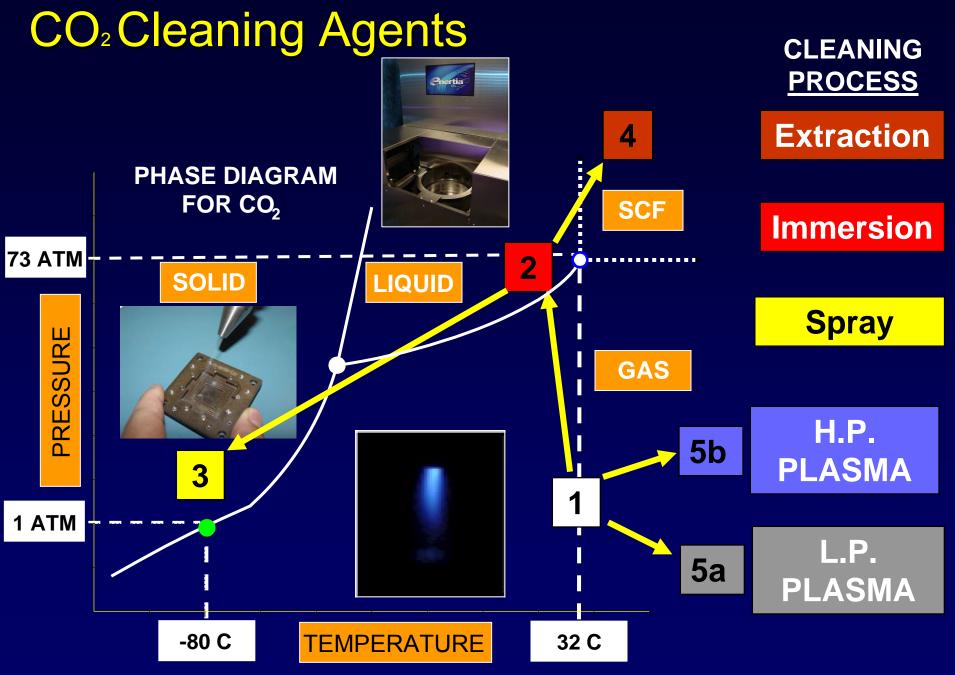
CO<sub>2</sub> is non-toxic, non-flammable and non-corrosive. Recycled CO<sub>2</sub> is exempt from the EPA Global Warming legislation.

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### CO<sub>2</sub> is Inexpensive

<u>Solvent</u>	Bulk Price Range <u>\$/kg</u>		
Carbon Dioxide	0.10 - 0.25		
Acetone	0.44 - 0.49		
Isopropyl Alcohol	0.75 - 0.88		
Methylene Chloride	0.80 - 1.25		
1,1,1-Trichloroethane	1.25 - 2.00		
n-Propyl Bromide	3.00 - 5.00		

Just pennies of CO<sub>2</sub> are used in composite spray formulations for a cleaning operation...

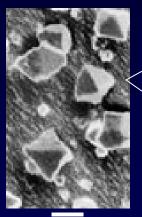


### **CO<sub>2</sub>Solvent Properties**

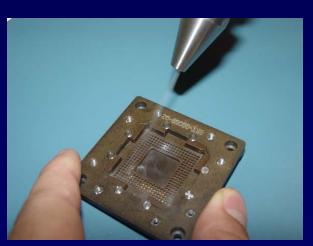
	Ca	Acetone		
DENSITY g/ml	Solid 1.6	Liquid 0.8	Supercritical 0.5	0.8
VISCOSITY mN-s/m <sup>2</sup>	-	0.07	0.03	0.32
SURFACE TENSION dynes/cm	5-10	5	0	24
SOLUBILITY MPa <sup>1/2</sup>	22	22	14	20

### Solid Carbon Dioxide

SEM Photomicrograph



1 µm



- Structure molecular crystal, angular, octahedron
- **Solvency** hydrocarbon-like, 22 MPa<sup>1/2</sup>
- Impact Phenomenon ablation and phase change (solid->gas, solid->liquid->gas)
- Chemistry can be modified with plasmas, liquids, solids, vapor-phase additives
- **Compressibility** incompressible
- Density 1.6 g/cm<sup>3</sup>
- Hardness 0.3 Hm (8 Hv)
- Particle Size < 0.5 microns to > 500 microns, range adjustable (coarse/fine)
  Impact Stress up to 60 MPa (8,700 psi)
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### **Conventional Snow Cleaning**

✓ CO<sub>2</sub> "snow" particles are **too small** and can't deliver the shear stress required to dislodge resistive contaminants.

✓ CO₂ snow sprays are too dense and cold (- 80 F), which tends to shield/freeze surface contamination ("Igloo Effect").

 ✓ CO₂ snow sprays discharge at a *high pressure* (800+ psi) that can damage structures at close proximity (needed for cleaning effectiveness with small particles).



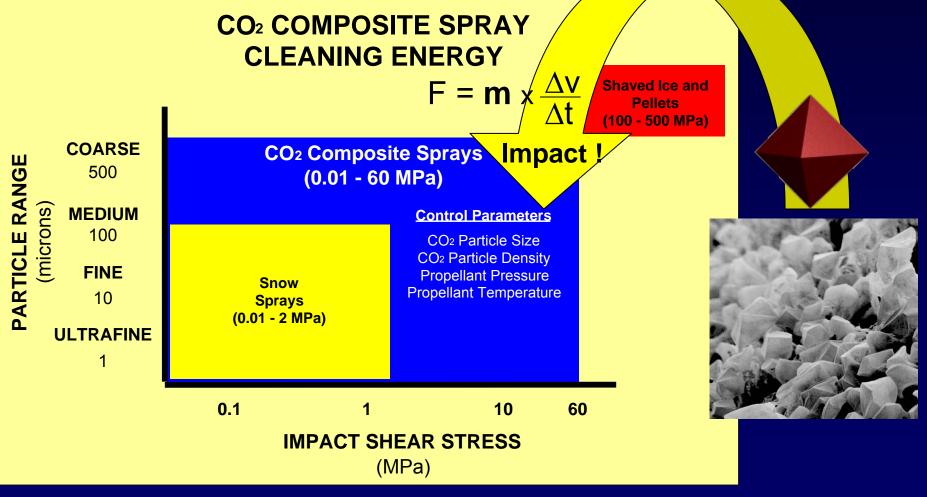


CO<sub>2</sub> composite spray technology is better suited to the contact cleaning task....Why?

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### First...Variable Particle Size and Density

Adjustable compositions of lean (high freq. impacts) energetic CO<sub>2</sub> particles (size control) and heated propellant gas...at low spray pressures (10 -120 psi).



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#### Second...Spray Composition Control

Additive(s)Gas(Chemical/<br/>Physical)(Propulsion/<br/>Heating)

Chemical Thermal Mechanical



Particle Size Chemistry Spray Density Temperature Pressure Distance/Angle Time

### **Third...Process Enhancement Tool**



CO<sub>2</sub> composite sprays easily adapt to and augment an existing probe maintenance program to increase overall cleaning process efficiency and effectiveness ....

#### Existing Cleaning and Inspection Process

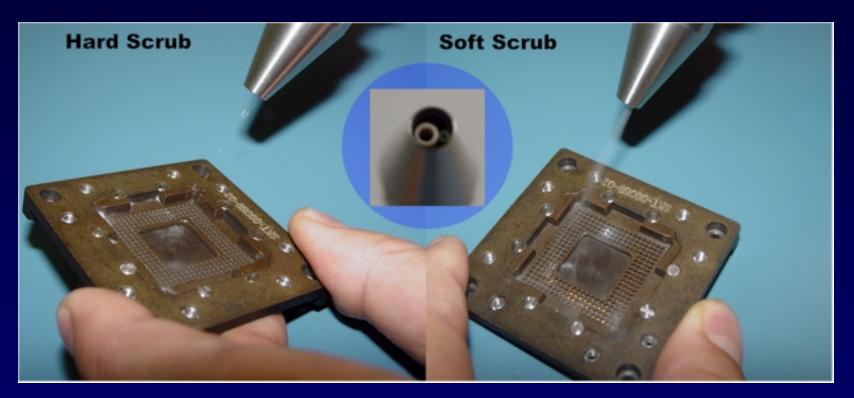
Composite sprays are additive without being mechanically destructive (energy control)...





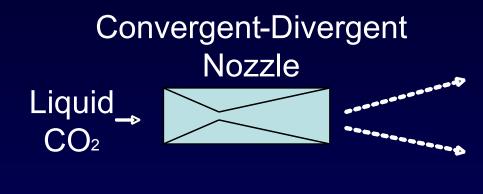


- Capillary condensation for particle size control
- Micro-metered mass flow for precise spray density control
- Clean hot propellant gas for pressure and temperature control
- Coaxial and Coanda composite spray nozzles
- Chemical co-solvents easily employed
- Hybrid CO<sub>2</sub> composite spray treatments Microabrasives, Laser, Atmospheric Plasma, Chemical Adjuncts, Brush



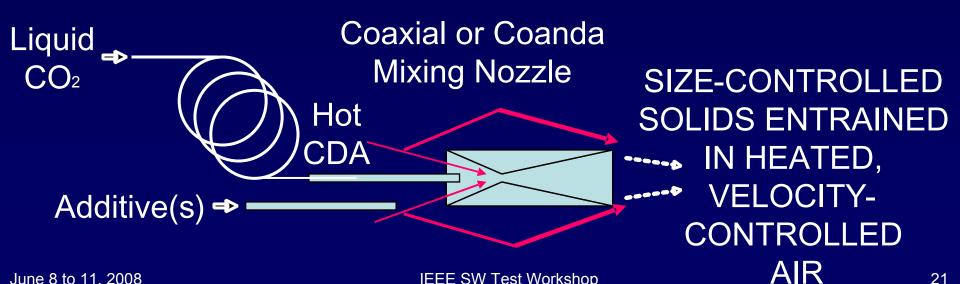
Lean Composite CO<sub>2</sub> Sprays, used in cooperation.

**SNOW SPRAYS** (Conventional)



**FINE SOLIDS ENTRAINED** IN COLD HIGH **VELOCITY** CO<sub>2</sub> GAS

#### **COMPOSITE SPRAYS**

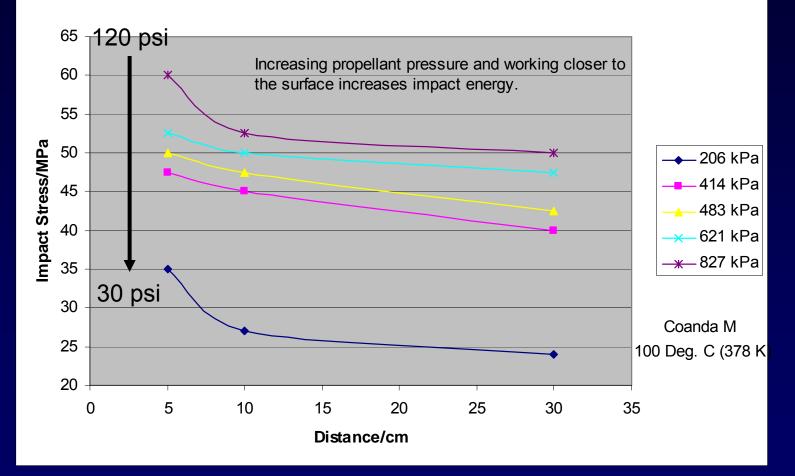


#### **Mechanical and Tribo-Chemical Cleaning Actions**

CO<sub>2</sub> composite spray cleaning process effectiveness and efficiency is controlled by:

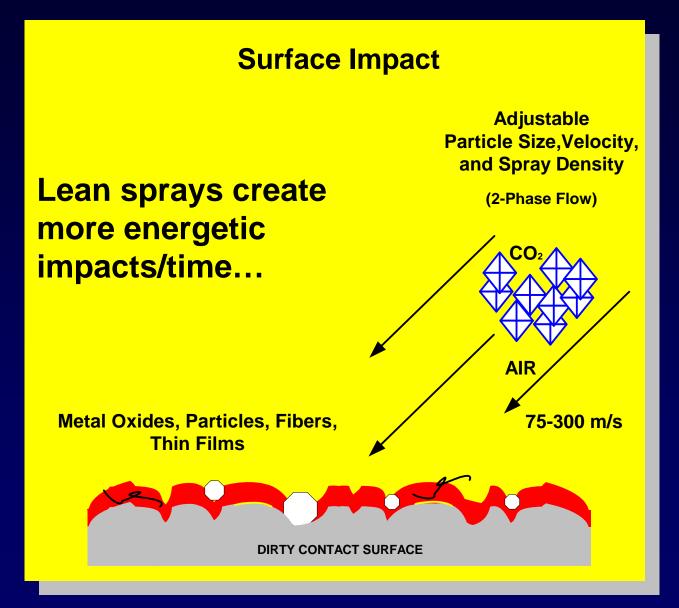
- ✓ Particle velocity
- ✓ Particle mass/size
- ✓ Spray chemistry
- ✓ Particle hardness (fine  $\rightarrow$  coarse)
- ✓ Particle shape (angular is better (stress conc.))
- ✓ Impact frequency
- ✓ Spray distance
- ✓ Time

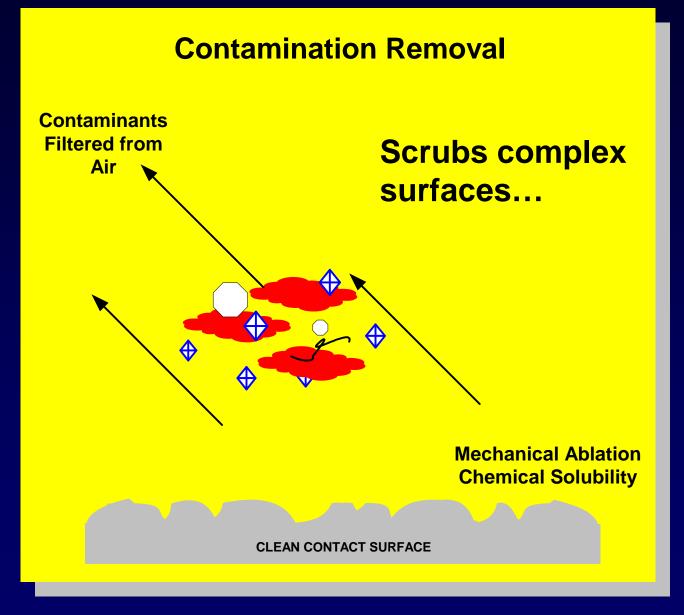
#### **Peak Impact Stress v. Propellant Pressure**



CO<sub>2</sub> composite spray cleaning energy varies with pressure, temperature, particle size and additive energy...

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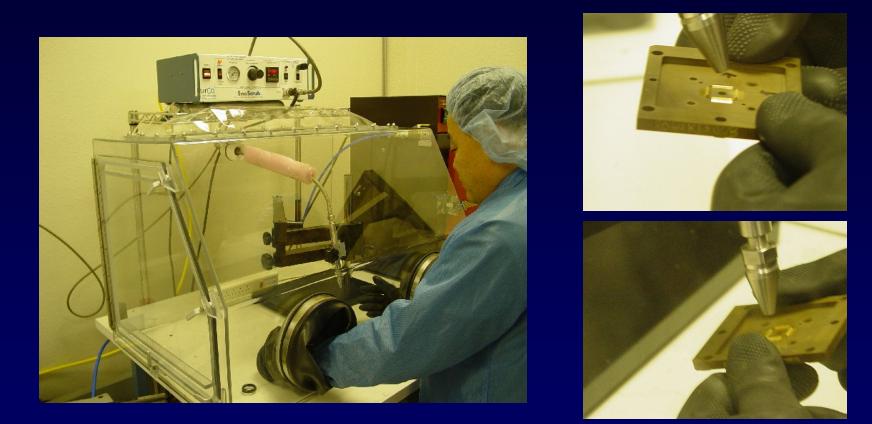
### **CO<sub>2</sub> Composite Spray Cleaning System**

Several CO<sub>2</sub> composite spray cleaning methods and processes under development for probe cards (and test sockets)...

Manual – Automated - Hybrids



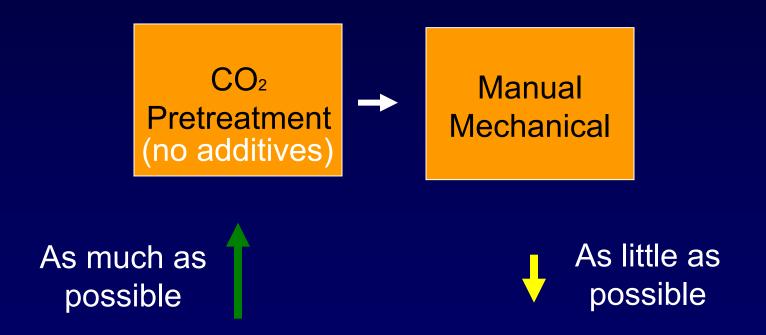


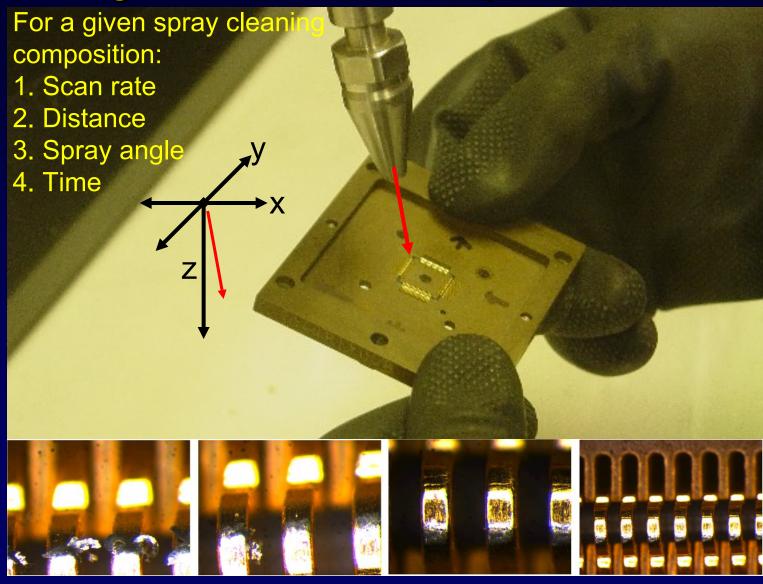


#### R&D System at customer site

Goal: Minimize or eliminate direct contact cleaning.

**Clean-during-Inspection** 



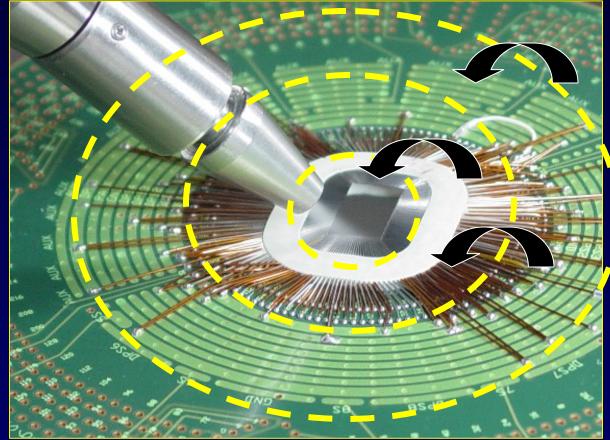


#### What should be cleaned ?

Best Practice: Contacts plus Peripheral Surfaces

#### **Contamination**

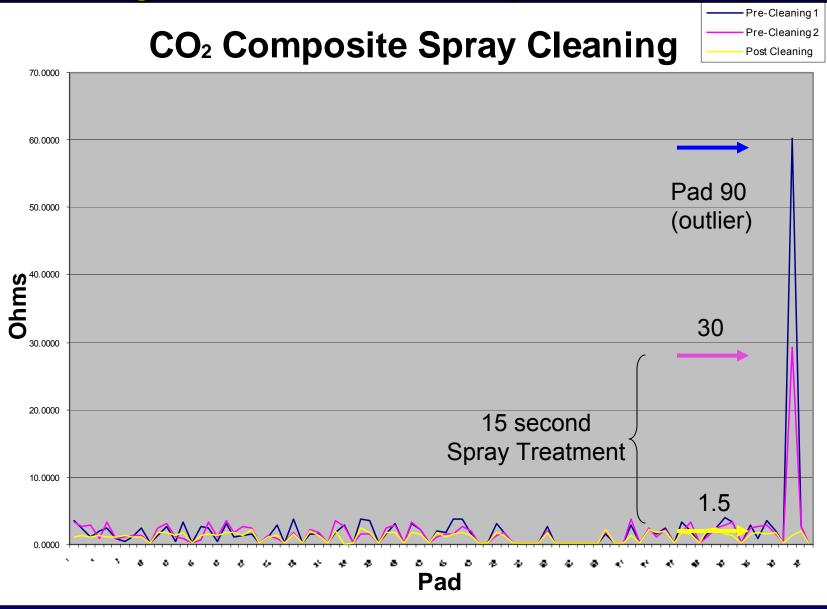
migrates through ES-Fields, thermal gradients, physical transfer modes...



Not cleaning the entire surface creates the potential for cross-contamination...

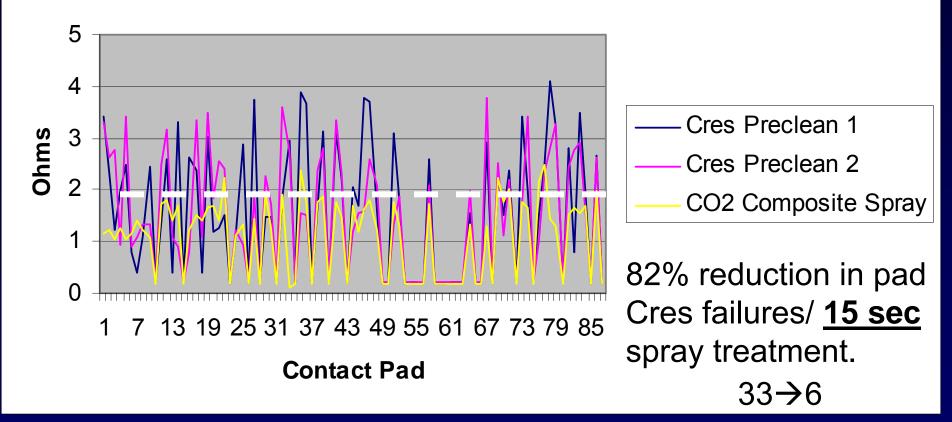
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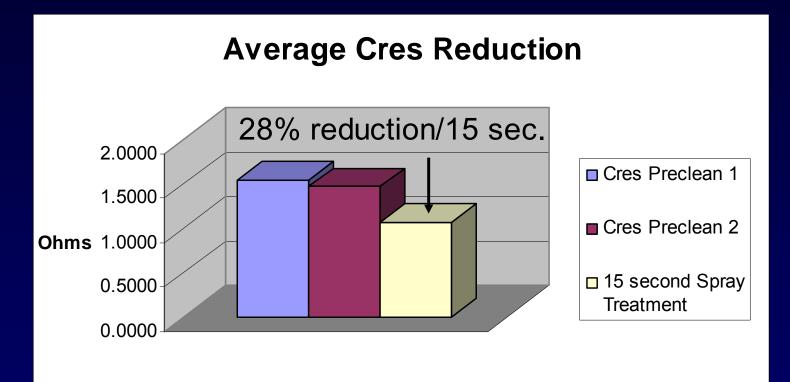


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**Pad Cres** 



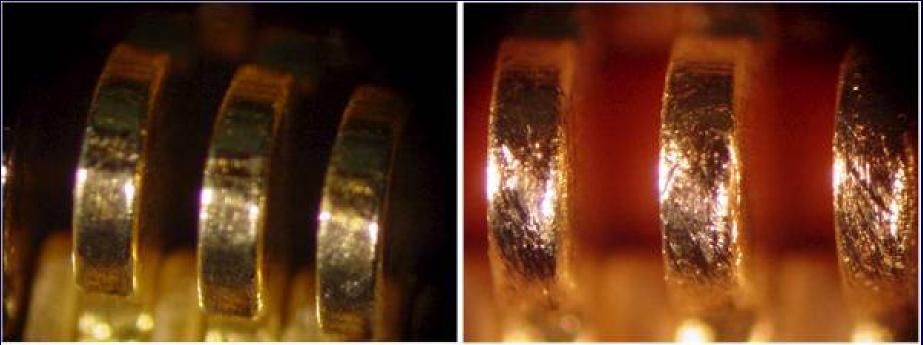
Outlier data (Pad 90) removed from data set



#### Outlier data (Pad 90) removed from data set.

#### Cleaning Action Before

After



#### Metal Oxides/Solder

#### **Cleaning Spray Parameters:**

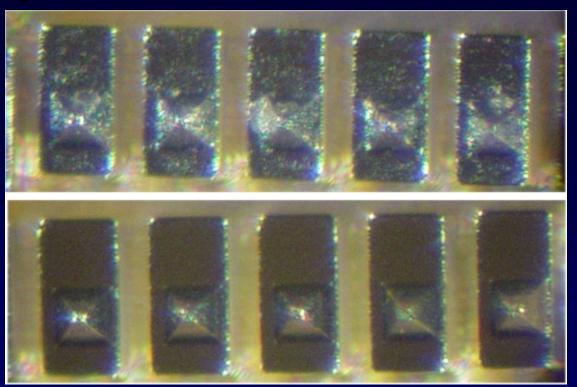
Spray Pressure/Temp: Cleaning Time/Distance: Chemistry:

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80 psi/120 C 1 minute/1 inch CDA, Coarse CO<sub>2</sub> Particles

### **Cleaning Action**

Before



After

#### Aluminum/Al<sub>2</sub>0<sub>3</sub>

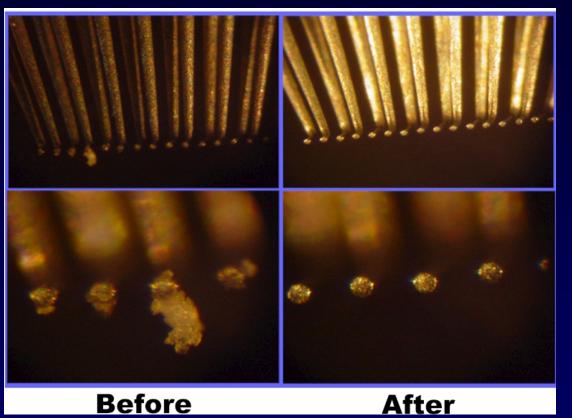
#### **Cleaning Spray Parameters:**

Spray Pressure/Temp: Cleaning Time/Distance: Chemistry:

70 psi/120 C 3 minutes/2 inches (robotic process) CDA, Fine CO<sub>2</sub> Particles

### **Cleaning Action**

Metal Oxides and Solder Flux



#### **Cleaning Spray Parameters:**

Spray Pressure/Temp: Cleaning Time/Distance: Chemistry: 40 psi/120 C 30 seconds/1.5 inches CDA, Fine CO<sub>2</sub> Particles

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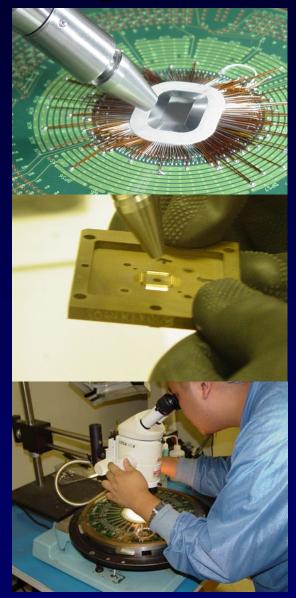
# **Cleaning Cost Reduction**



#### **Existing Process:**

- Easy to get lost under scope
- Surface contamination remains in complex topography (crevices)
- Potential physical damage to surfaces with brush
- Time intensive

### **Cleaning Cost Reduction**



#### **New Process:**

In combination with CO<sub>2</sub> pretreatment:

- Significant reduction in maintenance labor
- ✓ Cleaner surfaces...*faster*
- ✓ Much less direct contact
- ✓ Much less physical damage

### Wrap-up

- Composite CO<sub>2</sub> sprays are fully adjustable and provide quick, clean, and nondestructive contact cleaning.
- Worker- and equipment-safe cleaning process.
- Adaptable to existing cleaning processes.
   Minimizes manual cleaning, potential to replace mechanical contact treatments.
- Low cost-per-clean with a significant contact maintenance labor (time) reduction potential.



For more information:

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